

**STRESS RESISTANT LAND GRID ARRAY (LGA) MODULE
AND METHOD OF FORMING THE SAME**

ABSTRACT OF THE DISCLOSURE

An integrated circuit module, a land grid array module, and a method for forming the
5 module, include a substrate, which mounts one or more chips or discrete electronic components,
and a cap for covering the substrate, and including at least one protrusion coupled to the cap for
limiting the amount of flexing of the substrate during actuation. The at least one protrusion can
be either rigidly fixed to the cap or adjustably inserted through the cap.